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EPAS ID: PAT6162740

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the RECEIVING PARTY'S STREET ADDRESS previously recorded on Reel 052894 Frame 0508. Assignor(s) hereby confirms the RECEIVING PARTY'S STREET ADDRESS SHOULD BE CHANGED FROM "HUQINGPING" TO --HUQINGPING ROAD--..

CONVEYING PARTY DATA

Name	Execution Date
HESTIA POWER INC.	05/20/2020

RECEIVING PARTY DATA

Name:	SHANGHAI HESTIA POWER INC.
Street Address:	ROOM 1225, BLOCK B, FLOOR 12, BUILDING B, NO. 1-72, LANE 2855, HUQINGPING ROAD, QINGPU DISTRICT
City:	SHANGHAI
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	9368650

CORRESPONDENCE DATA

Fax Number: (703)621-7155

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7036217140

Email: mailroom@mg-ip.com,asc@mg-ip.com

Correspondent Name: MUNCY, GEISSLER, OLDS & LOWE, P.C.

Address Line 1: 4000 LEGATO RD., SUITE 310

Address Line 4: FAIRFAX, VIRGINIA 22033

ATTORNEY DOCKET NUMBER:	2450/3312PUS1
NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
SIGNATURE:	/Joe McKinney Muncy/
DATE SIGNED:	06/19/2020

Total Attachments: 4

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**United States Patent and Trademark Office**

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HESTIA POWER INC.	05/20/2020
RECEIVING PARTY DATA	
Name:	SHANGHAI HESTIA POWER INC.
Street Address:	ROOM 1225, BLOCK B, FLOOR 12, BUILDING B, NO. 1-72, LANE 2855, HUQINGPING, QINGPU DISTRICT
City:	SHANGHAI
State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	9368650
CORRESPONDENCE DATA	
Fax Number:	(703)621-7155
Phone:	7036217140

PATENT
REEL: 052987 FRAME: 0649

Email: mailroom@mg-ip.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: MUNCY, GEISSLER, OLDS & LOWE, PC
Address Line 1: 4000 LEGATO RD., SUITE 310
Address Line 4: FAIRFAX, VIRGINIA 22033

ATTORNEY DOCKET NUMBER:	2450/3312PUS1
NAME OF SUBMITTER:	JOE MCKINNEY MUNCY
Signature:	/Joe McKinney Muncy/
Date:	06/10/2020
Total Attachments: 2 source=2020-06-10-ASSIGN AS FILED#page1.tif source=2020-06-10-ASSIGN AS FILED#page2.tif	
RECEIPT INFORMATION	
EPAS ID:	PAT6146924
Receipt Date:	06/10/2020

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ASSIGNMENT

WHEREAS, **Hestia Power Inc.**, a corporation organized and existing under and by virtue of the laws of Taiwan, having an office at 6F-5, No.18, Puding Rd., Hsinchu City 300, Taiwan (R.O.C.) is the owner by previous assignment(s), of the entire undivided right, title and interest of the following invention(s):

U.S. Application No. 14/196,629 which issued as 9,018,640 on Apr. 28, 2015 titled **SILICON CARBIDE POWER DEVICE EQUIPPED WITH TERMINATION STRUCTURE**; and

U.S. Application No. 14/801,123 which issued as 9,368,650 on Jun. 14, 2016 titled **SIC JUNCTION BARRIER CONTROLLED SCHOTTKY RECTIFIER**; and

U.S. Application No. 14/668,299 which issued as 9,246,016 on Jan. 26, 2016 titled **SILICON CARBIDE SEMICONDUCTOR DEVICE**; and

U.S. Application No. 14/591,470 which issued as 9,685,552 on Jun. 20, 2017 titled **SILICON CARBIDE FIELD EFFECT TRANSISTOR**; and

U.S. Application No. 14/612,782 which issued as 9,373,713 on Jun. 21, 2016 titled **SILICON CARBIDE SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURE THEREOF**;

WHEREAS, **Shanghai Hestia Power Inc.**, a corporation organized and existing under and by virtue of the laws of China, having an office at Room 1225, block B, floor 12, Building B, No. 1-72, Lane 2855, Hujingping Road, Qingpu District, Shanghai, its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention(s) and in and to any Letters Patent(s) that may be granted therefore in the United States of America;

NOW THEREFORE, for and in consideration of the sum of Ten Dollars (\$10.00) lawful money of the United States and other valuable considerations, to me in hand paid, the receipt of and sufficiency whereof are hereby acknowledged, the said **Hestia Power Inc.**, has sold, assigned and transferred and does hereby sell, assign and transfer unto the said Assignee, its successors and assigns, its entire undivided right, title and interest in and to the said application(s) and the invention(s) therein contained, including all rights of action and damages for past infringement, and including the right to apply for any Letters Patent(s) in the United States of America and in all foreign countries on said invention(s) and including the right to claim the priority of the date of filing in the United States and any Letters Patent(s) that may issue thereon, or therefore, in the United States and foreign countries and all reissues, extensions, renewals, divisions and continuations thereof, to the full end of the term or terms for which said Letters Patent(s) may be issued, to be held and enjoyed by the said Assignee, its successors and assigns the same as it would have been held and enjoyed by **Hestia Power Inc.**, if this assignment(s) and sale had not been made.

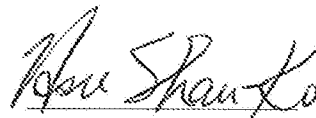
AND, **Hestia Power Inc.**, hereby authorizes and requests the Commissioner of Patents and Trademarks to issue all such Letters Patent(s) to the said Assignee, in accordance with this instrument of assignment.

Hestia Power Inc., hereby represents and warrants that there are no rights or interests outstanding inconsistent with the rights and interests granted herein and that Hestia Power Inc., will not execute any instrument or grant or transfer any rights or interests inconsistent therewith, and Hestia Power Inc., binds itself and its heirs, executors, administrators, employees and legal representatives, as the case may be, to execute and deliver to the said Assignee, its successors and assigns, any further documents or instruments and do any and all further acts that may be deemed necessary by the said Assignee, their successors and assigns to file applications for the said improvements and invention(s) in any country where it may elect to file such applications, and that may be necessary to vest in the said Assignee, its successors and assigns, the title herein conveyed, or intended so to be, and to enable such title to be recorded in the United States and foreign countries where such application or applications may be filed.

AND, Hestia Power Inc., further covenants and agrees, in consideration of the premises, that it, its executors and administrators will, at any time upon request, communicate to the said Assignee, its successors and assigns, any facts relating to the said invention(s) and improvements and the history thereof, known to it or its successors and assigns, and that it will testify as to the same in any interference or other proceeding when requested to do so by the said Assignee, its successors and assigns.

The undersigned hereby grants Muncy, Geissler, Olds & Lowe, P.C. the power to insert on this Assignment(s) any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.



(Signature)

Hsu Shan-Ko

(Typed or Printed Name)

Chairman

(Title)

May 20 2020

(Date)